

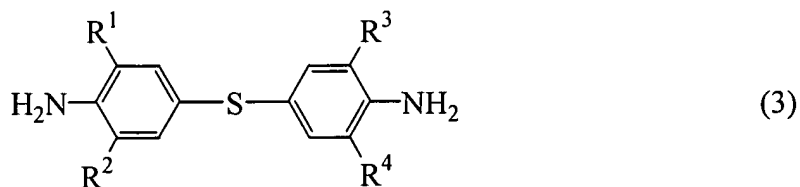
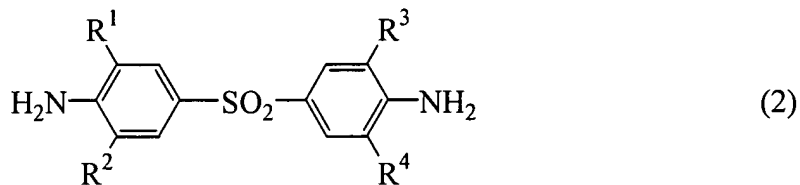
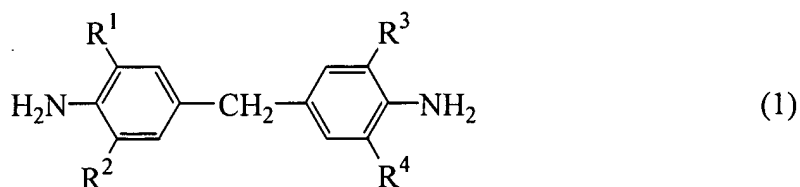
AMENDMENTS TO THE CLAIMS

The following listing of claims is complete and replaces all prior versions. Please amend the claims as follows:

1. (Currently amended) A liquid epoxy resin composition comprising

(A) 100 parts by weight of a liquid epoxy resin,

(B) an aromatic amine curing agent comprising at least 5% by weight of at least one aromatic amine compound having a purity of at least 99% selected from compounds having the following general formulae (1) to (3):



wherein each of R¹ to R⁴ is hydrogen or a monovalent hydrocarbon group having 1 to 6 carbon atoms,

the liquid epoxy resin (A) and the aromatic amine curing agent (B) being present in a molar ratio (A)/(B) from 0.7/1 to less than 0.9/1,

(C) 100 to 1,000 parts by weight of an inorganic filler, and

(D) an ester organic solvent having a boiling point of 130 to 250°C and having the general formula (4):



wherein R⁵ and R⁷ each are a monovalent hydrocarbon group having 1 to 6 carbon atoms, R⁶ is an alkylene group having 1 to 6 carbon atoms, and n is an integer of 0 to 3 in an amount of 0.5 to 10 parts by weight per 100 parts by weight of components (A) and (B) combined, and the composition having a toughness K_{1c} of at least 3.5.

2-3. (Canceled)

4. (Withdrawn) The composition of claim 1, further comprising a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average compositional formula (5):



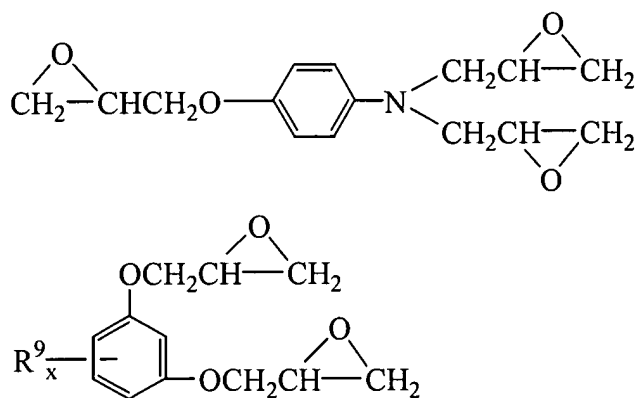
wherein R⁸ is a substituted or unsubstituted monovalent hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and $1.81 \leq a+b \leq 2.3$, said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly

attached to a silicon atom (i.e., SiH groups), by effecting addition of SiH groups to alkenyl groups.

5. (Withdrawn) A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

6. (Withdrawn) A flip chip type semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state as an underfill.

7. (New) The composition of claim 1 wherein the liquid epoxy resin is at least one selected from the group consisting of bisphenol type epoxy resins, naphthalene type epoxy resins, phenyl glycidyl ethers and an epoxy resin of the following structure:



wherein R^9 is hydrogen or a monovalent hydrocarbon group having 1 to 20 carbon atoms.